General Description

The SJS3416 uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a wide variety of applications.

Features

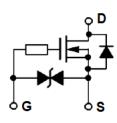
- Low Gate Charge
- High Power and current handing capability
- Lead free product is acquired
- ESD Rating: HBM 2KV

Application

Load Switch

Key Performance Parametes

Parameter	Value	Unit
V _{DS}	20	V
R _{DS(ON)_TYP}	12.3	mΩ
I _D	7.6	А
Q _G	9.1	nC







Schematic Diagram

SOT-23 view

Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJS3416	3416	SOT-23	Tape	\	\	3000 Pcs

Table 1. Absolute Maximum Ratings ($T_A=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	20	V
V _G S	Gate-Source Voltage (V _{DS} =0V)	±12	V
1-	Drain Current-Continuous(T _A =25°ℂ)	7.6	А
l _D	Drain Current-Continuous(T _A =100°C)	4.8	А
I _{DM} (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	30.4	А
D-	Maximum Power Dissipation(T _A =25°C)	1.3	W
P _D	Maximum Power Dissipation(T _A =100°C)	0.5	W
Eas	Avalanche energy (Note 2)	25	mJ
T _J , T _{STG}	Operating Junction and Storage Temperature Range	-55 To 150	င

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
$R_{ hetaJA}$	Thermal Resistance, Junction-to- Ambient		94	°C/W



Table 3. Electrical Characteristics ($T_J=25^{\circ}C$ unless otherwise noted)

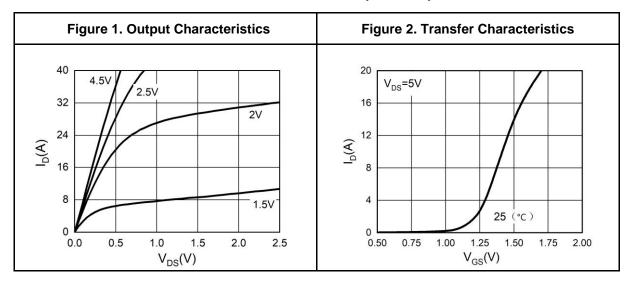
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	20			V
	Zana Oata Valtana Busin Oussant	V _{DS} =20V, V _{GS} =0V T _J =25°C			1	μΑ
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V T _J =125℃			100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±10V, V _{DS} =0V			±10	uA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	0.5		1	V
g FS	Forward Transconductance	V _{DS} =5V, I _D =5A		13.6		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =5A T _J =25°C		12.3	16	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =2.5V, I _D =4A T _J =25°C		15.6	20.7	mΩ
Dynamic Chara	cteristics					
Ciss	Input Capacitance			670		pF
Coss	Output Capacitance	$V_{DS}=10V,V_{GS}=0V,$ $f=1.0KHz$		150		pF
Crss	Reverse Transfer Capacitance			90		pF
Switching Para	meters					
t _{d(on)}	Turn-on Delay Time			11		nS
t _r	Turn-on Rise Time	V _{GS} =4.5V, V _{DS} =10V,		34		nS
$t_{d(off)}$	Turn-Off Delay Time	R_L =2Ω, R_{GEN} =3Ω		55		nS
t _f	Turn-Off Fall Time			51		nS
Q_g	Total Gate Charge			9.1		nC
Q _{gs}	Gate-Source Charge	V _{GS} =4.5V, V _{DS} =10V, I _D =5A		1.6		nC
Q_{gd}	Gate-Drain Charge			2		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current (Body Diode)				7.6	А
V_{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =5A			1.2	V

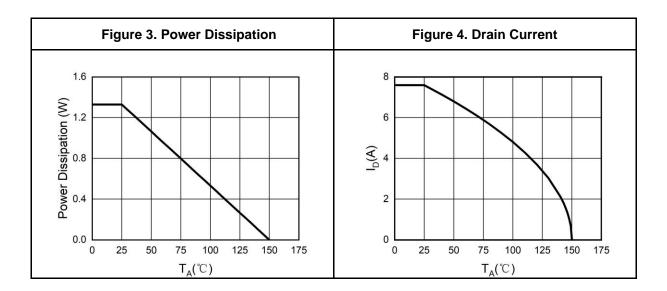
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature. Notes 2.E_{AS} condition: T_J =25°C, V_DD =10V, V_G =10V, Rg=25 Ω , L=0.5mH.

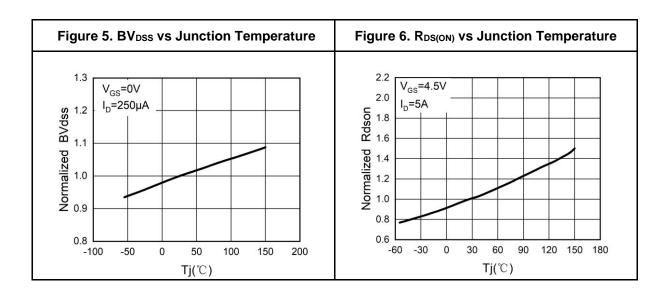
Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



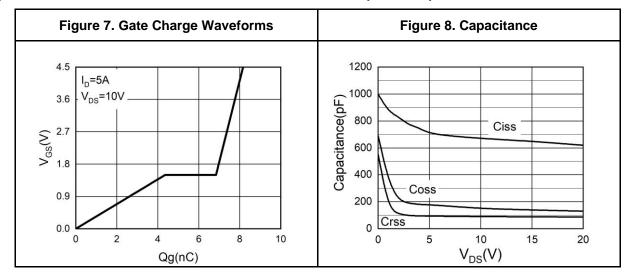
Typical Electrical And Thermal Characteristics (Curves)

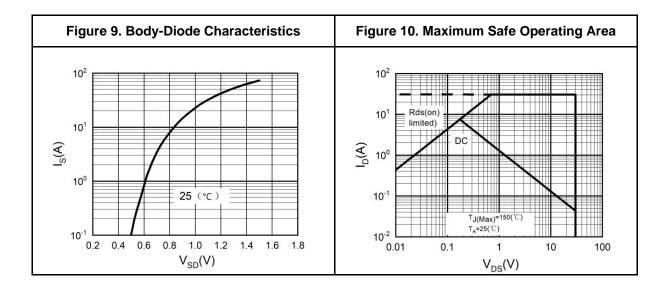






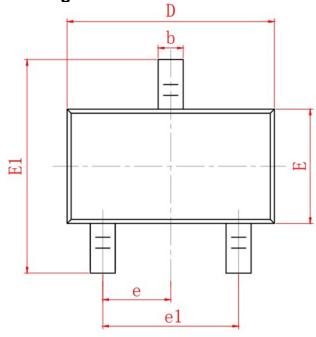
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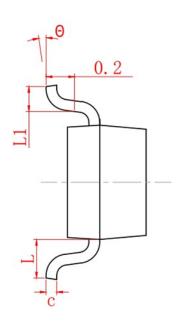


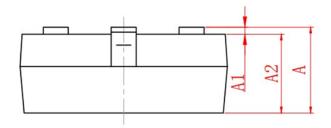




SOT-23 Package Information







SYMBOL	MIN	NOM	MAX	
A	0.90	1.05	1.20	
A1	0.00	0.05	0.10	
A2	0.90	1.00	1.10	
b	0.30	0.40	0.50	
С	0.08	0.10	0.15	
D	2.80	2.90	3.00	
E	1.20	1.30	1.40	
E1	2.30 2.40 2.50			
L	0.30 0.40 0.50			
θ	0°	5°	10°	
L1	0.55 REF			
е	0.95 BSC			
e1	1.90 REF			



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